

METHOD FOR MONITORING QUALITY OF AN INSULATION LAYER

Abstract

The present invention utilizes wafer acceptance testing equipment to fast monitor the quality of an insulation layer. A plurality of swing time-dependent DC ramping voltages are applied to one of the electrode plates in a capacitor and each corresponding leakage current is measured to calculate each corresponding β value. Then, a ratio of each β value is calculated and a β - voltage curve is plotted to actually simulate the device failure.